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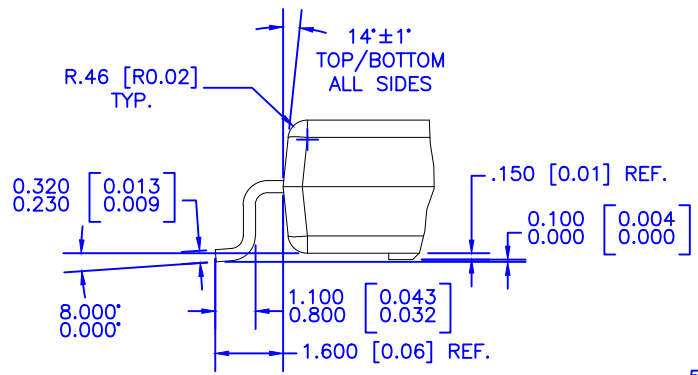
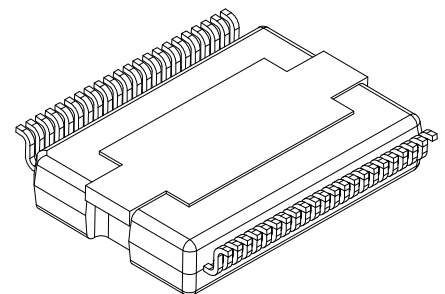
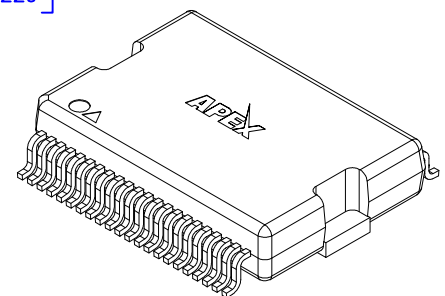
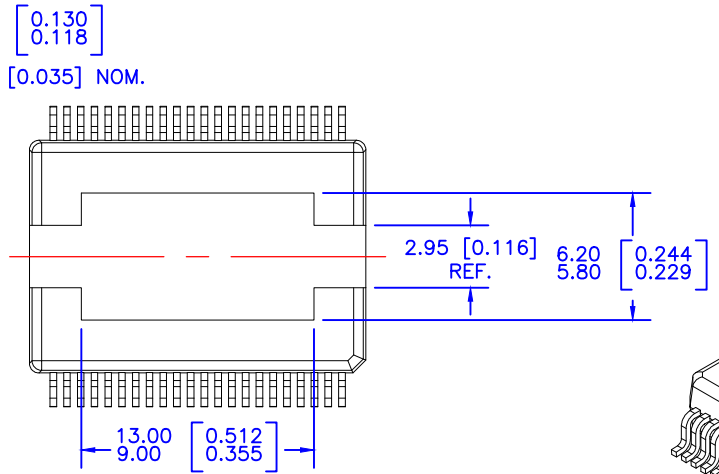
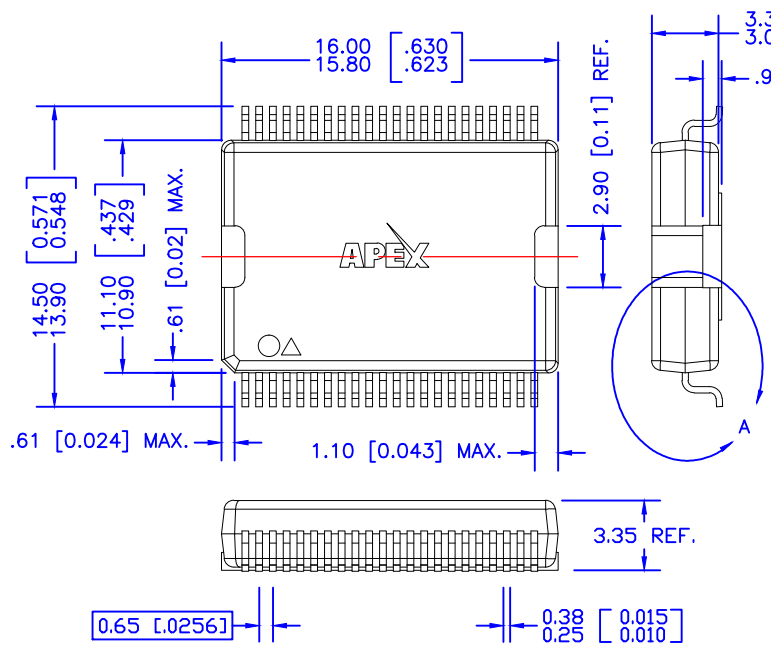
C

B

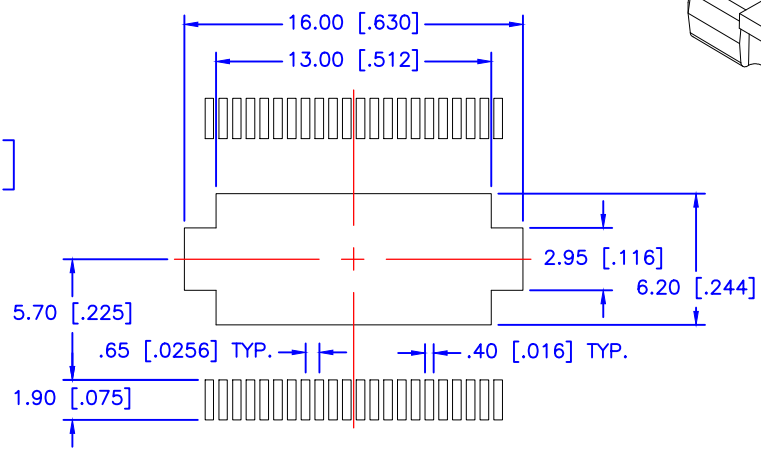
B

A

A



DETAIL A



SUGGESTED SURFACE MOUNT LAYOUT

NOTES:

1. Dimensions are millimeters & [inches].
2. Bracketed alternate units are for reference only.
3. Dimple on lid & ESD triangle denote pin 1.
4. Pins & Heat Slug: C19400 & C10200 copper with plated finish.
5. Mold compound: Epoxy
6. Package weight: .086 oz. [2.44 g]
7. Suggested surface mount layout for reference only.

TOLERANCES - UNLESS OTHERWISE SPECIFIED			TITLE: JEDEC MO-166, 44-pin HSOP SLUG-DN				MODEL:								
.XX = ±.01 [.254] .XXX = ±.005 [.127] ANG. = ±5°			SUBJECT: PACKAGE OUTLINE				HR								
ENGINEER:	J.MUTZ	DRAWN BY:	J.FAY	DCA:	16319	SH:	1	OF:	1	FILENAME:	HR	REV:	D	DATE:	04AUG16

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